



Embedded Fanless System



TIGER (L)

LEO

Back Panel Motherboard I/O



Blue-marked area is for extra functions

Back Panel Expansion I/O Possibilities & more



Including, but not limited to these functions

		TIGER (L)	LEO
Motherboard		3I770A (W)	3I380A
System Dimension (WxDxH)		190.8W x 195D x 59.4H mm	246W x 124D x 57H mm
Weight (Incl. M/B)		2.5 kg	1.22 kg
CPU		Intel Mobile Ivy Bridge processor	Intel Bay Trail-I E3825 1.33 GHz (Dual Core) Intel Bay Trail-I E3845 1.91 GHz (Quad Core)
Chipset		Intel Pather Point(PCH) QM77	
Memory	Type / Capacity	DDR3 1333 / 1600 MT/s	E3825 DDR3L 1066MT/s / E3845 DDR3L 1333MT/s
	SO-DIMM	1, Max up to 8GB	1 (Optional with on board memory) Up to 8GB
	On board memory	N/A	2 / 4GB
SSD Storage	mSATA	Yes	Yes
	On Board SSD	N/A	Optional
HDD Space		2.5" HDD x 1	2.5" HDD x 1
VGA		Yes	Yes
DVI / HDMI		HDMI	HDMI
USB		Built-in 4 x USB, expand up to 9 x USB (USB 3.0 x 2 + USB 2.0 x 7)	4
PS2 KB / MS		Optional	Optional
COM		6	3
Mini PCIe		2	2
SIM Card Holder		1	1
GPIO		4 DI / 4DO ; option to 8 DI / 8 DO	8DI / 8DO (optional)
Ethernet		2 x GbE	2 x Intel GbE
Mic-in / Line-out		Yes	Yes
Power Input		DC IN +12V ; +9V~+36V (optional)	DC IN +12V ; +9V~+36V (optional)
Expansion		3G / 4G, GPS, Bluetooth, WI-FI	3G / 4G, GPS, Bluetooth, WI-FI, I/O
Optional MB		3I860A / CW	3I847AW
Operating Temp.		0~45°C for HDD, -20°C~70°C for mSATA -20°C~60°C for SSD HDD	0~45°C for HDD, -20°C~70°C for mSATA -20°C~60°C for SSD HDD
Operating Humidity		5%~95% @ 60°C, non-condensing	5%~95% @ 60°C, non-condensing